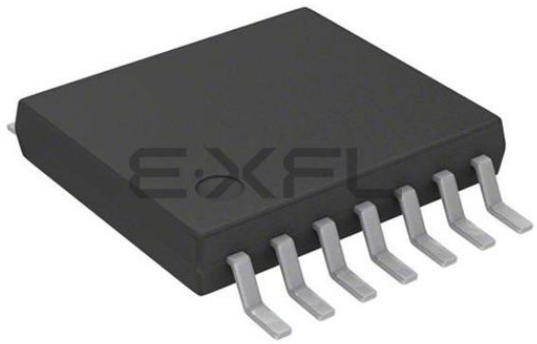

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 11x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	14-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	14-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f18324-e-st

- Up to 18 I/O Pins:
  - Individually programmable pull-ups
  - Slew rate control
  - Interrupt-on-change with edge-select
  - Input level selection control (ST or TTL)
  - Digital open-drain enable
- Peripheral Pin Select (PPS):
  - I/O pin remapping of digital peripherals
- Timer modules:
  - Timer0:
    - 8/16-bit timer/counter
    - Synchronous or asynchronous operation
    - Programmable prescaler/postscaler
    - Time base for capture/compare function
  - Timer1/3/5 with gate control:
    - 16-bit timer/counter
    - Programmable internal or external clock sources
    - Multiple gate sources
    - Multiple gate modes
    - Time base for capture/compare function
  - Timer2/4/6:
    - 8-bit timers
    - Programmable prescaler/postscaler
    - Time base for PWM function

Analog Peripherals

- 10-Bit Analog-to-Digital Converter (ADC):
  - 17 external channels
  - Conversion available during Sleep
- Comparator:
  - Two comparators
  - Fixed Voltage Reference at non-inverting input(s)
  - Comparator outputs externally accessible
- 5-Bit Digital-to-Analog Converter (DAC):
  - 5-bit resolution, rail-to-rail
  - Positive Reference Selection
  - Unbuffered I/O pin output
  - Internal connections to ADCs and comparators
- Voltage Reference:
  - Fixed Voltage Reference with 1.024V, 2.048V and 4.096V output levels

Flexible Oscillator Structure

- High-Precision Internal Oscillator:
  - Software-selectable frequency range up to 32 MHz
  - ±2% at nominal 4 MHz calibration point
- 4x PLL with External Sources
- Low-Power Internal 31 kHz Oscillator (LFINTOSC)
- External Low-power 32 kHz Crystal Oscillator (SOSC)
- External Oscillator Block with:
  - Three Crystal/Resonator modes up to 20 MHz
  - Three External Clock modes up to 20 MHz
  - Fail-Safe Clock Monitor:
    - Detects clock source failure
  - Oscillator Start-up Timer (OST)
    - Ensures stability of crystal oscillator sources

TABLE 4-4: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-31 (CONTINUED)

Address	Name	PIC16(L)F18324	PIC16(L)F18344	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
Bank 5													
CPU CORE REGISTERS; see Table 4-2 for specifics													
28Ch	ODCONA			—	—	ODCA5	ODCA4	—	ODCA2	ODCA1	ODCA0	--00 -000	--00 -000
28Dh	ODCONB	X	—	Unimplemented								—	—
		—	X	ODCB7	ODCB6	ODCB5	ODCB4	—	—	—	—	0000 ----	0000 ----
28Eh	ODCONC	X	—	—	—	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	--00 0000	--00 0000
		—	X	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000 0000	0000 0000
28Fh	—	—		Unimplemented								—	—
290h	—	—		Unimplemented								—	—
291h	CCPR1L			CCPR1<7:0>								xxxx xxxx	xxxx xxxx
292h	CCPR1H			CCPR1<15:8>								xxxx xxxx	xxxx xxxx
293h	CCP1CON			CCP1EN	—	CCP1OUT	CCP1FMT	CCP1MODE<3:0>				0-x0 0000	0-x0 0000
294h	CCP1CAP			—		—	—	CCP1CTS<3:0>				---- 0000	---- xxxx
295h	CCPR2L			CCPR2<7:0>								xxxx xxxx	xxxx xxxx
296h	CCPR2H			CCPR2<15:8>								xxxx xxxx	xxxx xxxx
297h	CCP2CON			CCP2EN	—	CCP2OUT	CCP2FMT	CCP2MODE<3:0>				0-x0 0000	0-x0 0000
298h	CCP2CAP			—	—	—	—	CCP2CTS<3:0>				---- 0000	---- xxxx
299h	—	—		Unimplemented								—	—
29Ah	—	—		Unimplemented								—	—
29Bh	—	—		Unimplemented								—	—
29Ch	—	—		Unimplemented								—	—
29Dh	—	—		Unimplemented								—	—
29Eh	—	—		Unimplemented								—	—
29Fh	CCPTMRS			C4TSEL<1:0>		C3TSEL<1:0>		C2TSEL<1:0>		C1TSEL<1:0>		0101 0101	0101 0101

Legend: x = unknown, u = unchanged, q =depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

Note 1: Only on PIC16F18324/18344.

2: Register accessible from both User and ICD Debugger.

7.0 OSCILLATOR MODULE

7.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 7-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz-crystal resonators and ceramic resonators. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, ECH, ECM, ECL) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources.

The RSTOSC bits of Configuration Word 1 determine the type of oscillator that will be used when the device is reset, including when it is first powered up.

The internal clock modes, LFINTOSC, HFINTOSC (set at 1 MHz), or HFINTOSC (set at 32 MHz) can be set through the RSTOSC bits.

If an external clock source is selected, the FEXTOSC bits of Configuration Word 1 must be used in conjunction with the RSTOSC bits to select the External Clock mode.

The external oscillator module can be configured in one of the following clock modes by setting the FEXTOSC<2:0> bits of Configuration Word 1:

1. ECL – External Clock Low-Power mode (<= 100 MHz)
2. ECM – External Clock Medium-Power mode (<= 8 MHz)
3. ECH – External Clock High-Power mode (<= 32 MHz)
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode (between 100 MHz and 4 MHz)
6. HS – High Gain Crystal or Ceramic Resonator mode (above 4 MHz)

The ECH, ECM, and ECL clock modes rely on an external logic level signal as the device clock source. The LP, XT, and HS clock modes require an external crystal or resonator to be connected to the device. Each mode is optimized for a different frequency range. The INTOSC internal oscillator block produces low and high-frequency clock sources, designated LFINTOSC and HFINTOSC. (see Internal Oscillator Block, Figure 7-1).

9.3.3 LOW POWER SLEEP MODE

The PIC16F18324/18344 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode.

The PIC16F18324/18344 allows the user to optimize the operating current in Sleep, depending on the application requirements.

Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. Depending on the configuration of this bit, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.3.3.1 Sleep Current vs. Wake-up Time

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking-up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The Normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.3.3.2 Peripheral Usage in Sleep

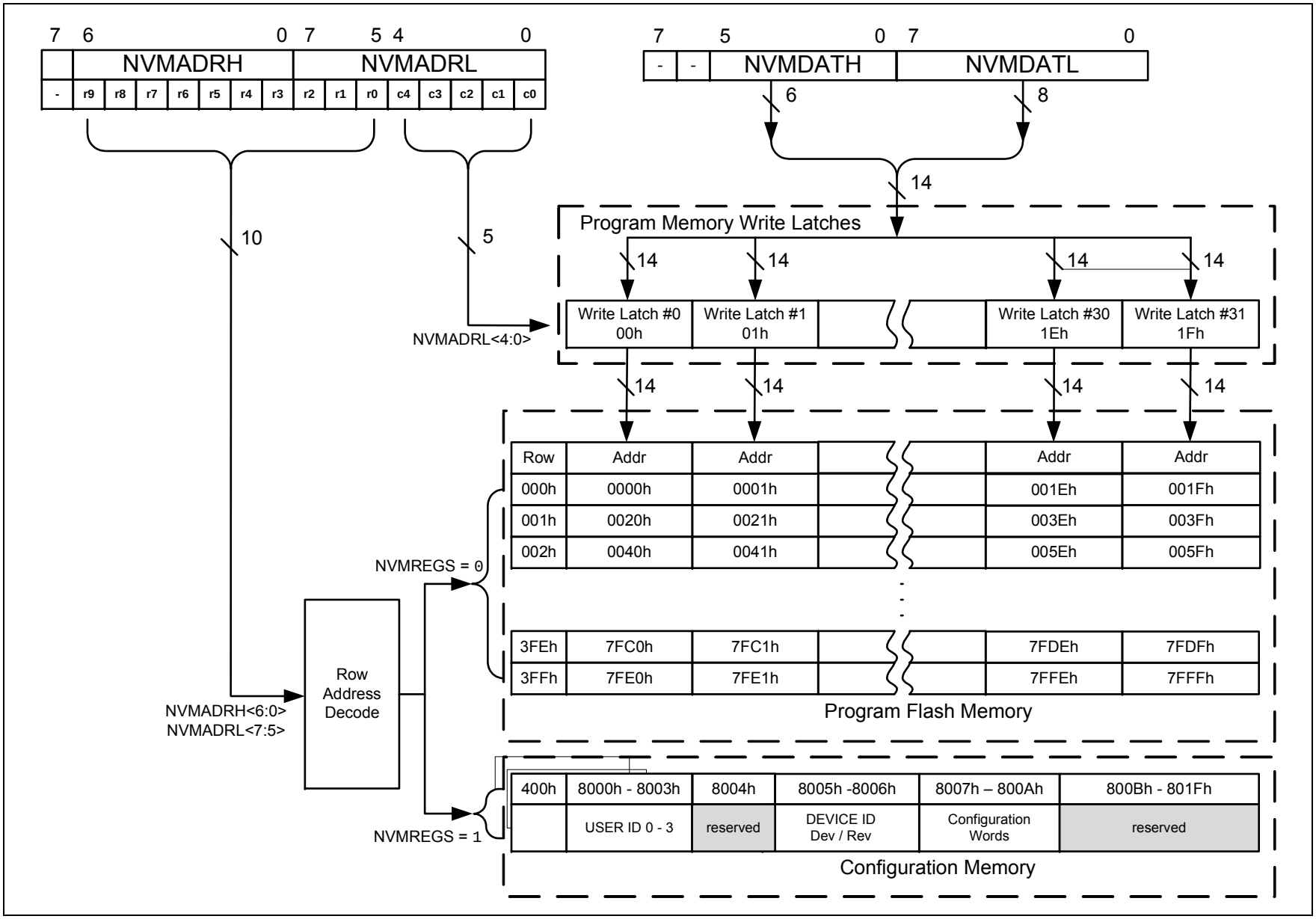
Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)

It is the responsibility of the end user to determine what is acceptable for their application when setting the VREGPM settings in order to ensure operation in Sleep.

Note:	The PIC16LF18324/18344 does not have a configurable Low-Power Sleep mode. PIC16LF18324/18344 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC16F18324/18344. See **Section 35.0 "Electrical Specifications"** for more information.

FIGURE 11-4: BLOCK WRITES TO PROGRAM FLASH MEMORY WITH 32 WRITE LATCHES



REGISTER 20-4: CWGxDAT: CWGx DATA INPUT SELECTION REGISTER

U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	DAT<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **DAT<3:0>:** CWG Data Input Selection bits

DAT	Data Source
0000	CWGxPPS
0001	C1OUT
0010	C2OUT
0011	CCP1
0100	CCP2
0101	CCP3
0110	CCP4
0111	PWM5
1000	PWM6
1001	NCO1
1010	CLC1
1011	CLC2
1100	CLC3
1101	CLC4
1110	Reserved
1111	Reserved

21.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLCx) provides programmable logic that operates outside the speed limitations of software execution. The logic cell takes up to 36 input signals and, through the use of configurable gates, reduces the 36 inputs to four logic lines that drive one of eight selectable single-output logic functions.

Input sources are a combination of the following:

- I/O pins
- Internal clocks
- Peripherals
- Register bits

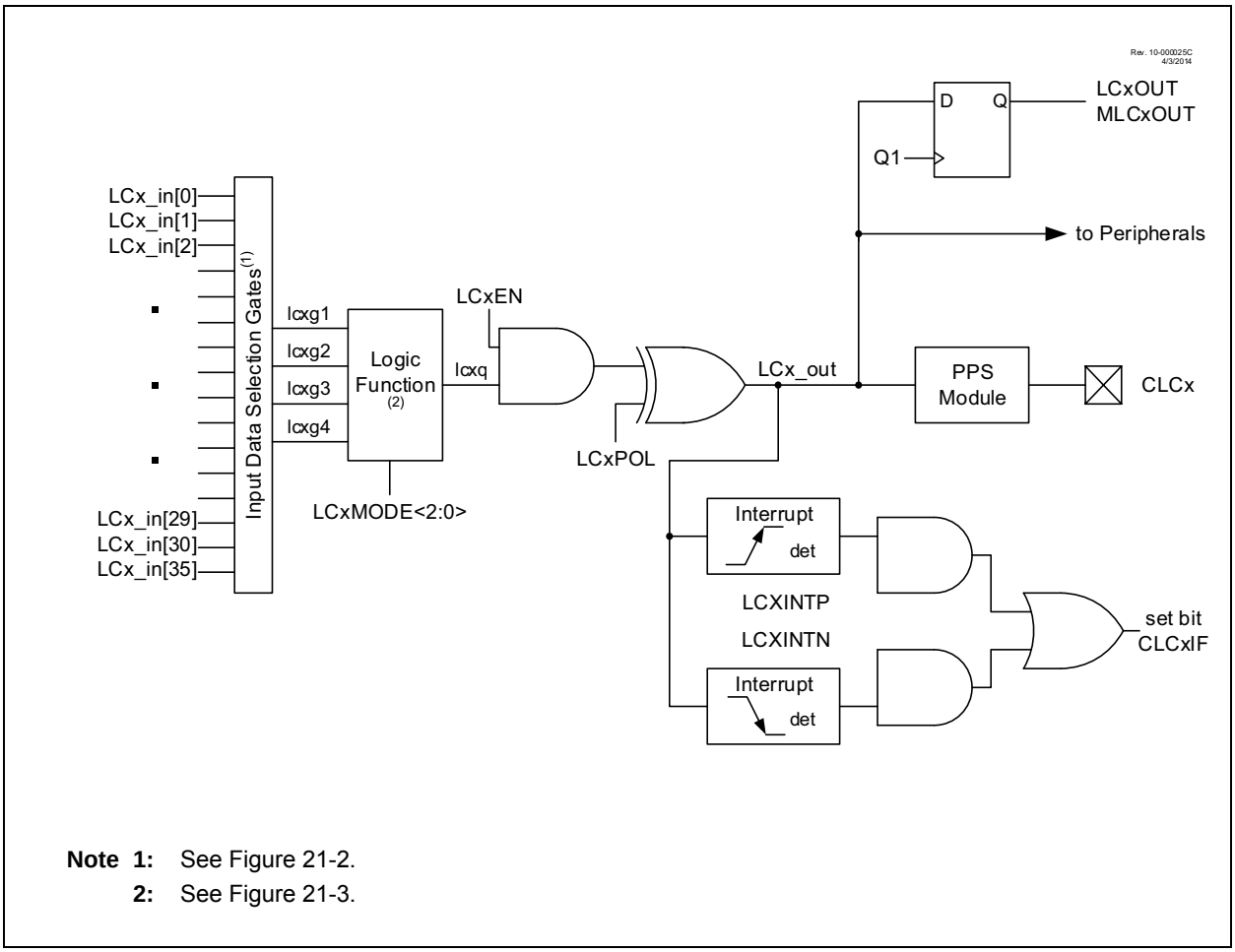
The output can be directed internally to peripherals and to an output pin.

Refer to Figure 21-1 for a simplified diagram showing signal flow through the CLCx.

Possible configurations include:

- Combinatorial Logic
  - AND
  - NAND
  - AND-OR
  - AND-OR-INVERT
  - OR-XOR
  - OR-XNOR
- Latches
  - S-R
  - Clocked D with Set and Reset
  - Transparent D with Set and Reset
  - Clocked J-K with Reset

FIGURE 21-1: CLCx SIMPLIFIED BLOCK DIAGRAM



Note 1: See Figure 21-2.
2: See Figure 21-3.

21.1 CLCx Setup

Programming the CLCx module is performed by configuring the four stages in the logic signal flow. The four stages are:

- Data selection
- Data gating
- Logic function selection
- Output polarity

Each stage is setup at run time by writing to the corresponding CLCx Special Function Registers. This has the added advantage of permitting logic reconfiguration on-the-fly during program execution.

21.1.1 DATA SELECTION

There are 36 signals available as inputs to the configurable logic.

Data selection is through four multiplexers as indicated on the left side of Figure 21-2. Data inputs in the figure are identified by the 'LCx_in' signal name.

Table 21-1 correlates the input number to the actual signal for each CLC module. The column labeled 'LCxDyS<5:0> Value' indicates the MUX selection code for the selected data input. LCxDyS is an abbreviation to identify the specific input multiplexer: LCxD1S<5:0> through LCxD4S<5:0>.

Data inputs are selected with CLCxSEL0 through CLCxSEL3 registers (Register 21-3 through Register 21-6).

TABLE 21-1: CLCx DATA INPUT SELECTION

LCxDyS<5:0> Value	CLCx Input Source
100011 [35]	TMR6/PR6 match
100010 [34]	TMR5 overflow
100001 [33]	TMR4/PR4 match
100000 [32]	TMR3 overflow
11111 [31]	FOSC
11110 [30]	HFINTOSC
11101 [29]	LFINTOSC
11100 [28]	ADCRC
11011 [27]	IOCIF int flag bit
11010 [26]	TMR2/PR2 match
11001 [25]	TMR1 overflow
11000 [24]	TMR0 overflow
10111 [23]	EUSART (DT) output
10110 [22]	EUSART (TX/CK) output
10101 [21]	Reserved
10100 [20]	Reserved
10011 [19]	SDA1
10010 [18]	SCL1
10001 [17]	PWM6 output
10000 [16]	PWM5 output
01111 [15]	CCP4 output
01110 [14]	CCP3 output
01101 [13]	CCP2 output
01100 [12]	CCP1 output
01011 [11]	CLKR output
01010 [10]	DSM output
01001 [9]	C2 output
01000 [8]	C1 output
00111 [7]	CLC4 output
00110 [6]	CLC3 output
00101 [5]	CLC2 output
00100 [4]	CLC1 output
00011 [3]	CLCIN3PPS
00010 [2]	CLCIN2PPS
00001 [1]	CLCIN1PPS
00000 [0]	CLCIN0PPS

REGISTER 21-10: CLCxGLS3: GATE 3 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG4D4T	LCxG4D4N	LCxG4D3T	LCxG4D3N	LCxG4D2T	LCxG4D2N	LCxG4D1T	LCxG4D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **LCxG4D4T:** Gate 3 Data 4 True (non-inverted) bit
1 = CLCIN3 (true) is gated into CLCx Gate 3
0 = CLCIN3 (true) is not gated into CLCx Gate 3

bit 6 **LCxG4D4N:** Gate 3 Data 4 Negated (inverted) bit
1 = CLCIN3 (inverted) is gated into CLCx Gate 3
0 = CLCIN3 (inverted) is not gated into CLCx Gate 3

bit 5 **LCxG4D3T:** Gate 3 Data 3 True (non-inverted) bit
1 = CLCIN2 (true) is gated into CLCx Gate 3
0 = CLCIN2 (true) is not gated into CLCx Gate 3

bit 4 **LCxG4D3N:** Gate 3 Data 3 Negated (inverted) bit
1 = CLCIN2 (inverted) is gated into CLCx Gate 3
0 = CLCIN2 (inverted) is not gated into CLCx Gate 3

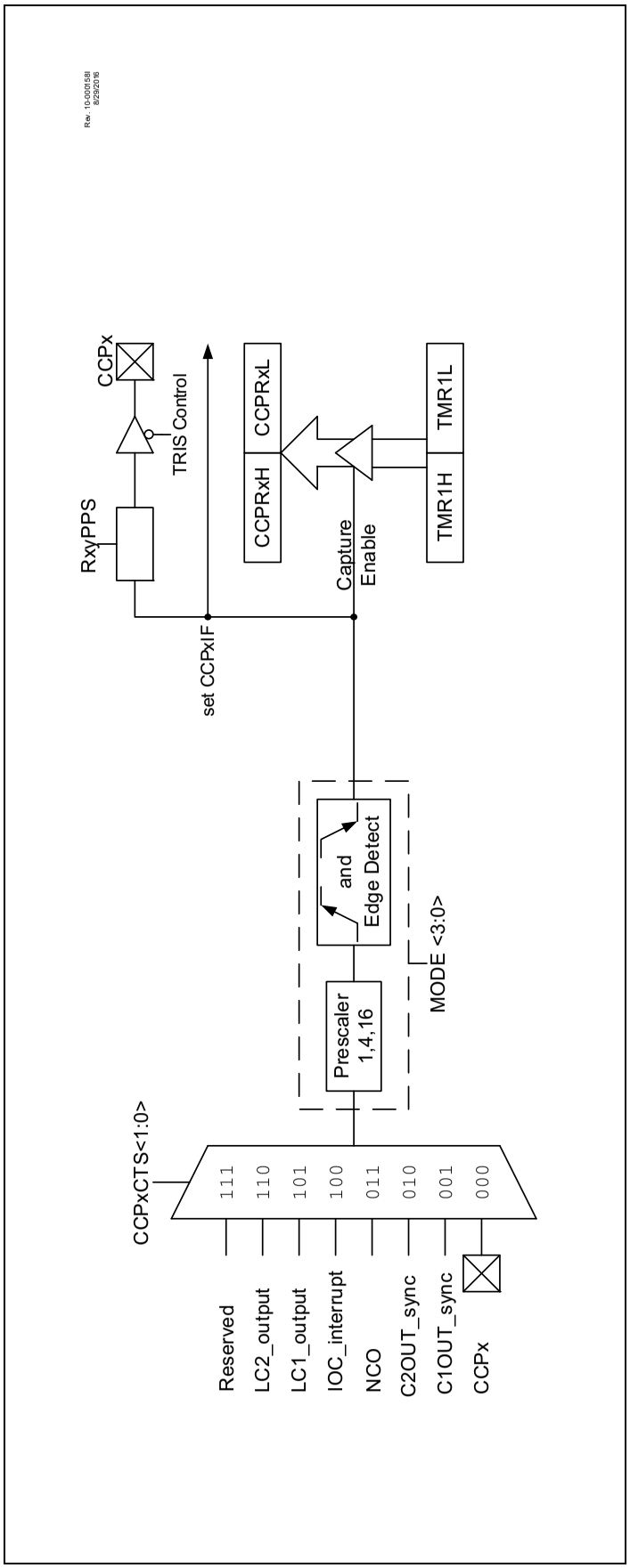
bit 3 **LCxG4D2T:** Gate 3 Data 2 True (non-inverted) bit
1 = CLCIN1 (true) is gated into CLCx Gate 3
0 = CLCIN1 (true) is not gated into CLCx Gate 3

bit 2 **LCxG4D2N:** Gate 3 Data 2 Negated (inverted) bit
1 = CLCIN1 (inverted) is gated into CLCx Gate 3
0 = CLCIN1 (inverted) is not gated into CLCx Gate 3

bit 1 **LCxG4D1T:** Gate 3 Data 1 True (non-inverted) bit
1 = CLCIN0 (true) is gated into CLCx Gate 3
0 = CLCIN0 (true) is not gated into CLCx Gate 3

bit 0 **LCxG4D1N:** Gate 3 Data 1 Negated (inverted) bit
1 = CLCIN0 (inverted) is gated into CLCx Gate 3
0 = CLCIN0 (inverted) is not gated into CLCx Gate 3

FIGURE 29-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



REGISTER 29-3: CCPRxL REGISTER: CCPx REGISTER LOW BYTE

R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x
CCPRxL<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0

CCPxMODE = Capture mode
CCPRxL<7:0>: Captured value of TMR1/3/5L
CCPxMODE = Compare mode
CCPRxL<7:0>: LS Byte compared to TMR1/3/5L
CCPxMODE = PWM modes when CCPxFMT = 0
CCPRxL<7:0>: CCPW<7:0> – Pulse-width Least Significant eight bits
CCPxMODE = PWM modes when CCPxFMT = 1
CCPRxL<7:6>: CCPW<1:0> – Pulse-width Least Significant two bits
CCPRxL<5:0>: Not used.

REGISTER 29-4: CCPRxH REGISTER: CCPx REGISTER HIGH BYTE

R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x
CCPRxH<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0

CCPxMODE = Capture mode
CCPRxH<7:0>: Captured value of TMR1/3/5H
CCPxMODE = Compare mode
CCPRxH<7:0>: MS Byte compared to TMR1/3/5H
CCPxMODE = PWM modes when CCPxFMT = 0
CCPRxH<7:2>: Not used
CCPRxH<1:0>: CCPW<9:8> – Pulse-width Most Significant two bits
CCPxMODE = PWM modes when CCPxFMT = 1
CCPRxH<7:0>: CCPW<9:2> – Pulse-width Most Significant eight bits

30.2.4 SPI SLAVE MODE

In Slave mode, the data is transmitted and received as external clock pulses appear on SCK. When the last bit is latched, the SSP1IF interrupt flag bit is set.

Before enabling the module in SPI Slave mode, the clock line must match the proper Idle state. The clock line can be observed by reading the SCK pin. The Idle state is determined by the CKP bit of the SSP1CON1 register.

While in Slave mode, the external clock is supplied by the external clock source on the SCK pin. This external clock must meet the minimum high and low times as specified in the electrical specifications.

While in Sleep mode, the slave can transmit/receive data. The shift register is clocked from the SCK pin input and when a byte is received, the device will generate an interrupt. If enabled, the device will wake-up from Sleep.

30.2.4.1 Daisy-Chain Configuration

The SPI bus can sometimes be connected in a daisy-chain configuration. The first slave output is connected to the second slave input, the second slave output is connected to the third slave input, and so on. The final slave output is connected to the master input. Each slave sends out, during a second group of clock pulses, an exact copy of what was received during the first group of clock pulses. The whole chain acts as one large communication shift register. The daisy-chain feature only requires a single Slave Select line from the master device.

Figure 30-7 shows the block diagram of a typical daisy-chain connection when operating in SPI mode.

In a daisy-chain configuration, only the most recent byte on the bus is required by the slave. Setting the BOEN bit of the SSP1CON3 register will enable writes to the SSP1BUF register, even if the previous byte has not been read. This allows the software to ignore data that may not apply to it.

30.2.5 SLAVE SELECT SYNCHRONIZATION

The Slave Select can also be used to synchronize communication. The Slave Select line is held high until the master device is ready to communicate. When the Slave Select line is pulled low, the slave knows that a new transmission is starting.

If the slave fails to receive the communication properly, it will be reset at the end of the transmission, when the Slave Select line returns to a high state. The slave is then ready to receive a new transmission when the Slave Select line is pulled low again. If the Slave Select line is not used, there is a risk that the slave will eventually become out of sync with the master. If the slave misses a bit, it will always be one bit off in future transmissions. Use of the Slave Select line allows the slave and master to align themselves at the beginning of each transmission.

The $\overline{SS}$ pin allows a Synchronous Slave mode. The SPI must be in Slave mode with $\overline{SS}$ pin control enabled (SSP1CON1<3:0> = 0100).

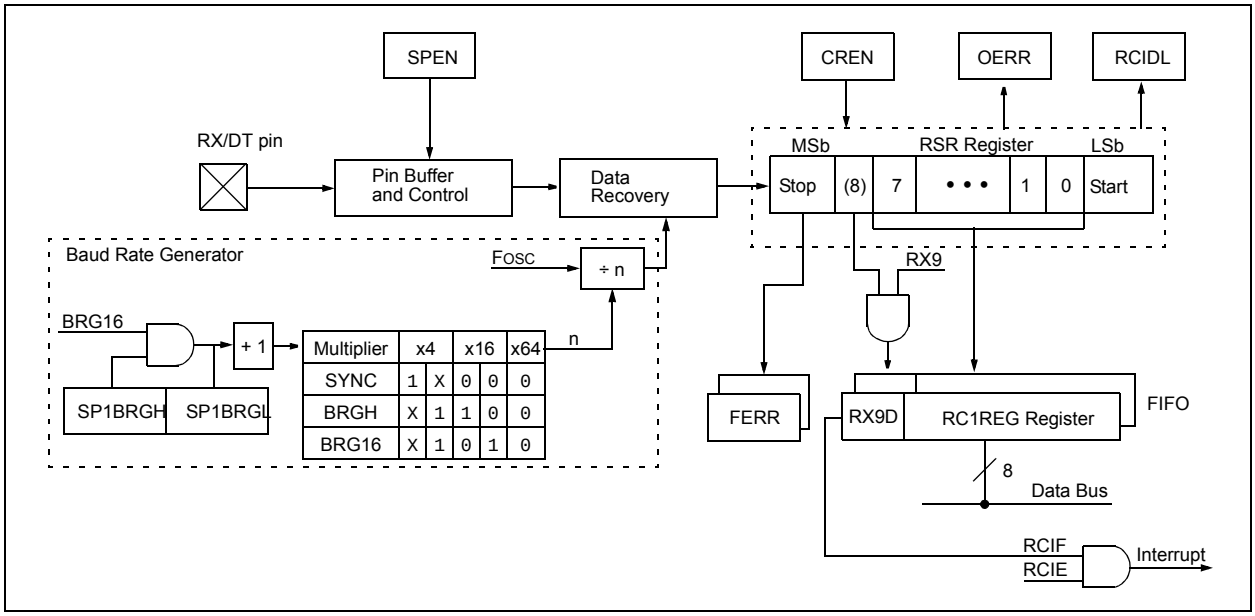
When the $\overline{SS}$ pin is low, transmission and reception are enabled and the SDO pin is driven.

When the $\overline{SS}$ pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte and becomes a floating output. External pull-up/pull-down resistors may be desirable depending on the application.

Note 1:	When the SPI is in Slave mode with $\overline{SS}$ pin control enabled (SSP1CON1<3:0> = 0100), the SPI module will reset if the $\overline{SS}$ pin is set to VDD.
2:	When the SPI is used in Slave mode with CKE set; the user must enable $\overline{SS}$ pin control.
3:	While operated in SPI Slave mode the SMP bit of the SSP1STAT register must remain clear.

When the SPI module resets, the bit counter is forced to '0'. This can be done by either forcing the $\overline{SS}$ pin to a high level or clearing the SSPEN bit.

FIGURE 31-2: EUSART1 RECEIVE BLOCK DIAGRAM



The operation of the EUSART1 module is controlled through three registers:

- Transmit Status and Control (TX1STA)
- Receive Status and Control (RC1STA)
- Baud Rate Control (BAUD1CON)

These registers are detailed in Register 31-1, Register 31-2 and Register 31-3, respectively.

The RX and CK input pins are selected with the RXPPS and CKPPS registers, respectively. TX, CK, and DT output pins are selected with each pin's RxyPPS register. Since the RX input is coupled with the DT output in Synchronous mode, it is the user's responsibility to select the same pin for both of these functions when operating in Synchronous mode. The EUSART1 control logic will control the data direction drivers automatically.

31.1.2.8 Asynchronous Reception Setup

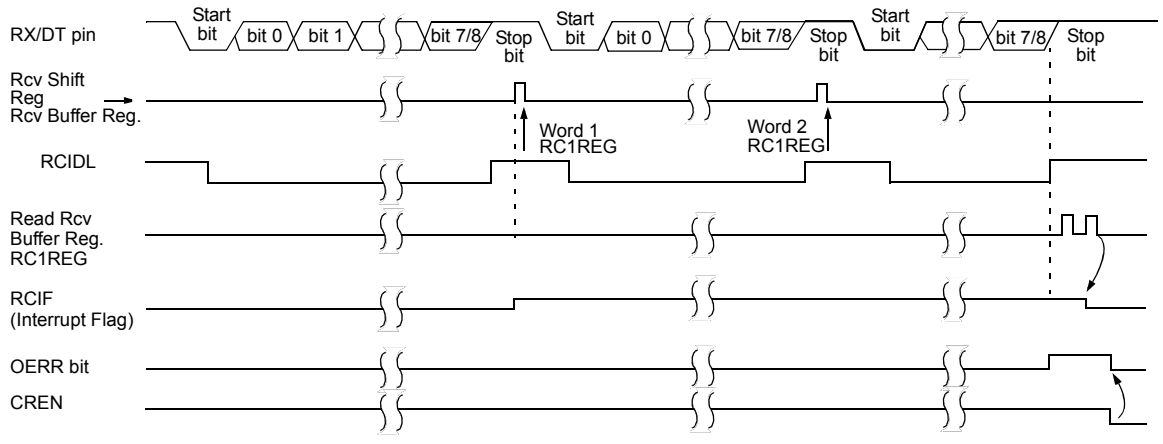
1. Initialize the SP1BRGH, SP1BRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 31.3 "EUSART1 Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RC1STA register to get the error flags and, if 9-bit data reception is enabled, the ninth data bit.
9. Get the received eight Least Significant data bits from the receive buffer by reading the RC1REG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

31.1.2.9 9-bit Address Detection Mode Setup

This mode would typically be used in RS-485 systems. To set up an Asynchronous Reception with Address Detect Enable:

1. Initialize the SP1BRGH, SP1BRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 31.3 "EUSART1 Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the ninth bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RC1STA register to get the error flags. The ninth data bit will always be set.
10. Get the received eight Least Significant data bits from the receive buffer by reading the RC1REG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

FIGURE 31-5: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RC1REG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

31.4 EUSART1 Synchronous Mode

Synchronous serial communications are typically used in systems with a single master and one or more slaves. The master device contains the necessary circuitry for baud rate generation and supplies the clock for all devices in the system. Slave devices can take advantage of the master clock by eliminating the internal clock generation circuitry.

There are two signal lines in Synchronous mode: a bidirectional data line and a clock line. Slaves use the external clock supplied by the master to shift the serial data into and out of their respective receive and transmit shift registers. Since the data line is bidirectional, synchronous operation is half-duplex only. Half-duplex refers to the fact that master and slave devices can receive and transmit data but not both simultaneously. The EUSART1 can operate as either a master or slave device.

Start and Stop bits are not used in synchronous transmissions.

31.4.1 SYNCHRONOUS MASTER MODE

The following bits are used to configure the EUSART1 for synchronous master operation:

- SYNC = 1
- CSRC = 1
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TX1STA register configures the device for synchronous operation. Setting the CSRC bit of the TX1STA register configures the device as a master. Clearing the SREN and CREN bits of the RC1STA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RC1STA register enables the EUSART1.

31.4.1.1 Master Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a master transmits the clock on the TX/CK line. The TX/CK pin output driver is automatically enabled when the EUSART1 is configured for synchronous transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One clock cycle is generated for each data bit. Only as many clock cycles are generated as there are data bits.

31.4.1.2 Clock Polarity

A clock polarity option is provided for Microwire compatibility. Clock polarity is selected with the SCKP bit of the BAUD1CON register. Setting the SCKP bit sets the clock Idle state as high. When the SCKP bit is set, the data changes on the falling edge of each clock. Clearing the SCKP bit sets the Idle state as low. When the SCKP bit is cleared, the data changes on the rising edge of each clock.

31.4.1.3 Synchronous Master Transmission

Data is transferred out of the device on the RX/DT pin. The RX/DT and TX/CK pin output drivers are automatically enabled when the EUSART1 is configured for synchronous master transmit operation.

A transmission is initiated by writing a character to the TX1REG register. If the TSR still contains all or part of a previous character the new character data is held in the TX1REG until the last bit of the previous character has been transmitted. If this is the first character, or the previous character has been completely flushed from the TSR, the data in the TX1REG is immediately transferred to the TSR. The transmission of the character commences immediately following the transfer of the data to the TSR from the TX1REG.

Each data bit changes on the leading edge of the master clock and remains valid until the subsequent leading clock edge.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

31.4.1.4 Synchronous Master Transmission Set-up

1. Initialize the SP1BRGH, SP1BRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 31.3 "EUSART1 Baud Rate Generator (BRG)"**).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Disable Receive mode by clearing bits SREN and CREN.
4. Enable Transmit mode by setting the TXEN bit.
5. If 9-bit transmission is desired, set the TX9 bit.
6. If interrupts are desired, set the TXIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
7. If 9-bit transmission is selected, the ninth bit should be loaded in the TX9D bit.
8. Start transmission by loading data to the TX1REG register.

33.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process, allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- MCLR/VPP
- VDD
- VSS

In Program/Verify mode the program memory, data EEPROM, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the **"***PIC16(L)F183XX Memory Programming Specification***"** (DS40001738).

33.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on MCLR/VPP to VIHH.

33.2 Low-Voltage Programming Entry Mode

The Low-Voltage Programming Entry mode allows the PIC® Flash MCUs to be programmed using VDD only, without high voltage. When the LVP bit of Configuration Words is set to '1', the low-voltage ICSP programming entry is enabled. To disable the Low-Voltage ICSP mode, the LVP bit must be programmed to '0'. The LVP bit can only be reprogrammed to '0' by using the High-Voltage Programming mode.

Entry into the Low-Voltage Programming Entry mode requires the following steps:

1. MCLR is brought to VIL.
2. A 32-bit key sequence is presented on ICSPDAT, while clocking ICSPCLK.

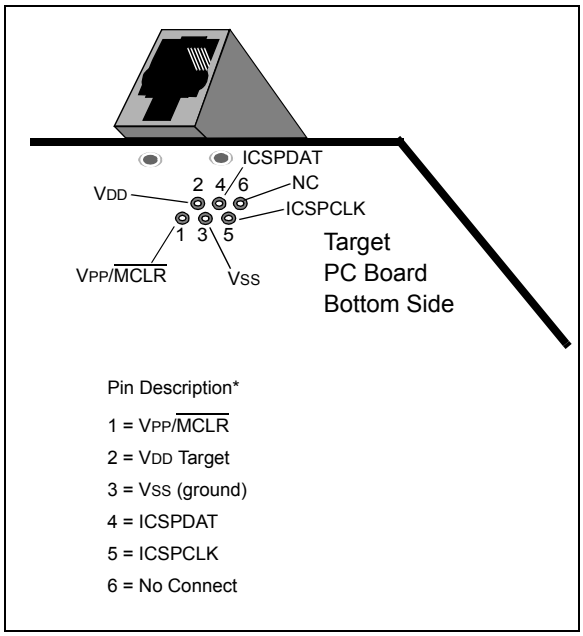
Once the key sequence is complete, MCLR must be held at VIL for as long as Program/Verify mode is to be maintained.

If low-voltage programming is enabled (LVP = 1), the MCLR Reset function is automatically enabled and cannot be disabled. See **Section 6.4 "MCLR**" for more information.

33.3 Common Programming Interfaces

Connection to a target device is typically done through an ICSP™ header. A commonly found connector on development tools is the RJ-11 in the 6P6C (6-pin, 6-connector) configuration. See Figure 33-1.

FIGURE 33-1: ICD RJ-11 STYLE CONNECTOR INTERFACE



Another connector often found in use with the PICkit™ programmers is a standard 6-pin header with 0.1 inch spacing. Refer to Figure 33-2.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 33-3 for more information.

RETLW **Return with literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Description: The W register is loaded with the 8-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.

Words: 1

Cycles: 2

Example:

```
CALL TABLE;W contains table
    ;offset value
•   ;W now has table value
•
•
ADDWF PC  ;W = offset
RETLW k1  ;Begin table
RETLW k2  ;
•
•
•
RETLW kn  ; End of table
```

TABLE

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC

Status Affected: None

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.

RLF **Rotate Left f through Carry**

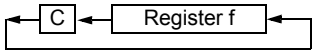
Syntax: [*label*] RLF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RLF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

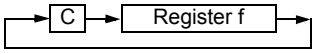
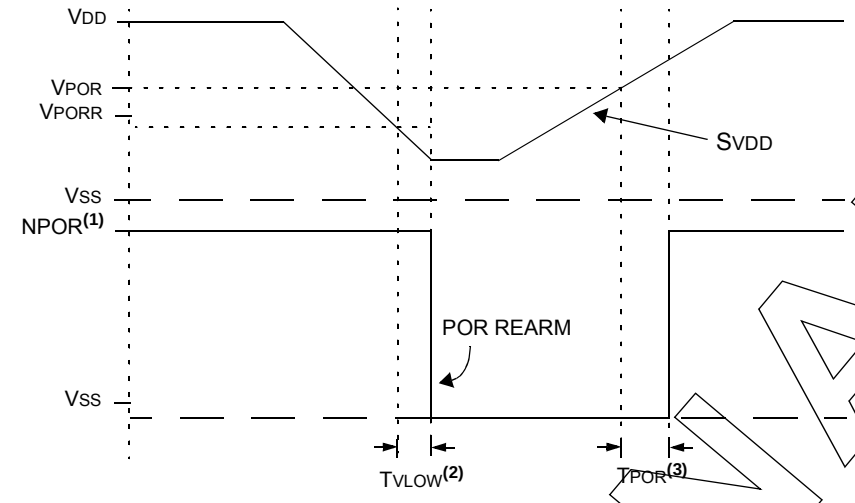


FIGURE 35-3: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

TABLE 35-3: POWER-DOWN CURRENTS (I_{PD})(1,2,3)

PIC16LF18324/18344			Standard Operating Conditions (unless otherwise stated)						
PIC16F18324/18344			Standard Operating Conditions (unless otherwise stated) VREGPM = 1						
Param. No.	Symbol	Device Characteristics	Min.	Typ.†	Max. +85°C	Max. +125°C	Units	Conditions	
								V_{DD}	Notes
D200	I_{PD}	I_{PD} Base	—	0.05	2	9	µA	3.0V	
D200	I_{PD}	I_{PD} Base	—	0.8	4	12	µA	3.0V	
			—	13.0	22	27	µA	3.0V	VREGM = 0
D201	I_{PD_WDT}	Low-Frequency Internal Oscillator/WDT	—	0.8	5	13	µA	3.0V	
D201	I_{PD_WDT}	Low-Frequency Internal Oscillator/WDT	—	0.9	5	13	µA	3.0V	
D202	I_{PD_SOSC}	Secondary Oscillator (SOSC)	—	0.6	5	13	µA	3.0V	
D202	I_{PD_SOSC}	Secondary Oscillator (SOSC)	—	0.8	9	15	µA	3.0V	
D203	I_{PD_FVR}	FVR	—	40	47	47	µA	3.0V	
D203	I_{PD_FVR}	FVR	—	33	44	44	µA	3.0V	
D204	I_{PD_BOR}	Brown-out Reset (BOR)	—	12	17	19	µA	3.0V	
D204	I_{PD_BOR}	Brown-out Reset (BOR)	—	12	18	20	µA	3.0V	
D205	I_{PD_LPBOR}	Low Power Brown-out Reset (LPBOR)	—	3	5	13	µA	3.0V	
D205	I_{PD_LPBOR}	Low Power Brown-out Reset (LPBOR)	—	4	5	13	µA	3.0V	
D207	I_{PD_ADCA}	ADC – Active	—	0.9	5	13	µA	3.0V	ADC is converting(4)
D207	I_{PD_ADCA}	ADC – Active	—	0.9	5	13	µA	3.0V	ADC is converting(4)
D208	I_{PD_CMP}	Comparator	—	32	43	45	µA	3.0V	
D208	I_{PD_CMP}	Comparator	—	31	42	44	µA	3.0V	

* These parameters are characterized but not tested.

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: All peripheral currents listed are on a per-peripheral basis if more than one instance of a peripheral is available.

4: ADC clock source is ADCRC.

TABLE 35-5: I/O AND CLOCK TIMING SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.†**	**Max.**	**Units**	**Conditions**
High Voltage Entry Programming Mode Specifications							
MEM01	V_{IHH}	Voltage on $\overline{MCLR}/V_{PP}$ pin to enter Programming mode	—	—	—	V	**Note 2**
MEM02	I_{PPGM}	Current on $\overline{MCLR}/V_{PP}$ pin during Programming mode	—	—	—	uA	**Note 2**
Programming Mode Specifications							
MEM10	V_{BE}	V_{DD} for Bulk Erase	—	2.7	—	V	
MEM11	I_{DDPGM}	Supply Current during Programming Operation	—	—	—	V	
Data EEPROM Memory Specifications							
MEM20	E_D	DataEE Byte Endurance	100k	—	—	E/W	-40°C ≤ T_A ≤ 85°C
MEM21	T_{D_RET}	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
MEM22	N_{D_REF}	Total Erase/Write Cycles before Refresh	—	—	100k	E/W	
MEM23	V_{D_RW}	V_{DD} for Read or Erase/Write Operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM24	T_{D_BEW}	Byte Erase and Write Cycle Time	—	4.0	5.0	ms	
Program Flash Memory Specifications							
MEM30	E_P	Flash Memory Cell Endurance	10k	—	—	E/W	-40°C ≤ T_A ≤ 85°C **(Note 1)**
MEM31	E_{PHEF}	High-Endurance Flash Memory Cell Endurance	100k	—	—	E/W	TBD
MEM32	T_{P_RET}	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
MEM33	V_{P_RD}	V_{DD} for Read Operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM34	V_{P_REW}	V_{DD} for Row Erase or Write Operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM35	T_{P_REW}	Self-Timed Row Erase or Self-Timed Write	—	2.0	2.5	ms	

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Flash Memory Cell Endurance for the Flash memory is defined as: One Row Erase operation and one Self-Timed Write.

2: Required only if CONFIG[3].LVP is disabled.